

## STS7NF60L

# N-CHANNEL 60V - 0.017 Ω - 7.5A SO-8 STripFET™ II POWER MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	ID
STS7NF60L	60 V	< 0.0195 Ω	7.5 A

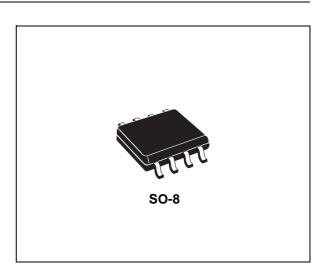
- TYPICAL  $R_{DS}(on) = 0.017 \Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- LOW THRESHOLD DRIVE

#### **DESCRIPTION**

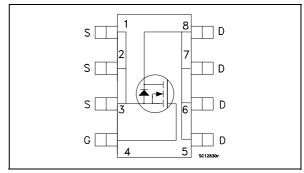
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

#### **APPLICATIONS**

- DC MOTOR DRIVE
- DC-DC CONVERTERS
- BATTERY MANAGEMENT IN NOMADIC **EQUIPMENT**
- POWER MANAGEMENT IN PORTABLE/DESKTOP PCs



#### **INTERNAL SCHEMATIC DIAGRAM**



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	60	V
$V_{DGR}$	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	60	V
$V_{GS}$	Gate- source Voltage	± 16	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	7.5	А
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 100°C	4.7	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	30	А
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	2.5	W
E <sub>AS</sub> (1)	Single Pulse Avalanche Energy	350	mJ

<sup>(•)</sup> Pulse width limited by safe operating area.

(1) Starting  $T_j = 25 \text{ °C}$ ,  $I_D = 7.5 \text{ A V}_{DD} = 30 \text{ V}$ 

April 2002 1/8

#### THERMAL DATA

Rthj-amb(#)	Thermal Resistance Junction-ambient Max	50	°C/W
Tj	Maximum Operating Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55 to 150	°C

<sup>(#)</sup> When Mounted on 1 inch² FR-4 board, 2 oz of Cu and  $t \leq 10 \mbox{ sec.}$ 

### **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

#### OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max Rating $V_{DS}$ = Max Rating $T_{C}$ = 125°C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 16 V			±100	nA

#### ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V V <sub>GS</sub> = 5 V	I <sub>D</sub> = 3.5 A I <sub>D</sub> = 3.5 A		0.017 0.019	0.0195 0.0215	Ω Ω

#### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub>	Forward Transconductance	$V_{DS} = 15 \text{ V}$ $I_{D} = 3.5 \text{ A}$		13		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$ , $f = 1 MHz$ , $V_{GS} = 0$		1700 300 100		pF pF pF

#### **ELECTRICAL CHARACTERISTICS** (continued)

#### SWITCHING ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time	$\begin{array}{ccc} V_{DD} = 30 \text{ V} & I_D = 3.5 \text{ A} \\ R_G = 4.7  \Omega & V_{GS} = 4.5 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{array}$		15 27		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD}$ = 48V $I_D$ 7.5A $V_{GS}$ =4.5V (see test circuit, Figure 2)		25 4.5 7	34	nC nC nC

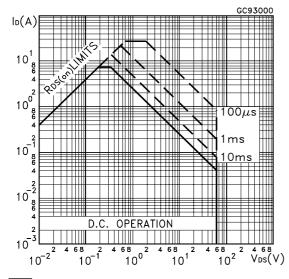
#### SWITCHING OFF (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		47 20		ns ns

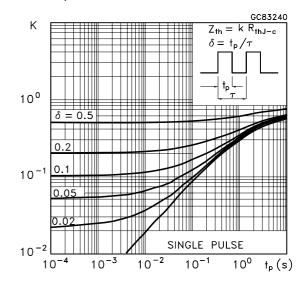
#### SOURCE DRAIN DIODE (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				7.5 30	A A
V <sub>SD</sub>	Forward On Voltage	$I_{SD} = 7.5 \text{ A}$ $V_{GS} = 0$			1.2	V
t <sub>rr</sub> Q <sub>rr</sub> IRRM	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD}$ =7.5 A di/dt = 100A/µs $V_{DD}$ = 20 V $T_j$ = 150°C (see test circuit, Figure 3)		55 110 3.9		ns nC A

#### Safe Operating Area

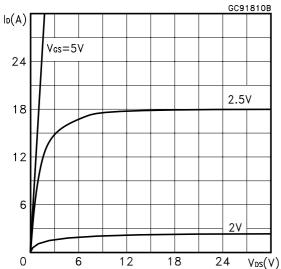


#### Thermal Impedance

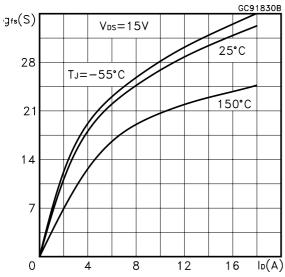


<sup>(\*)</sup> Pulse width ≤ 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

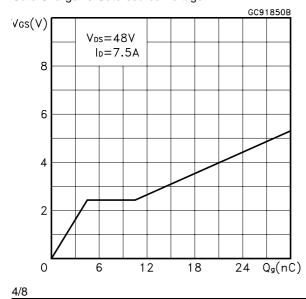
# Output Characteristics



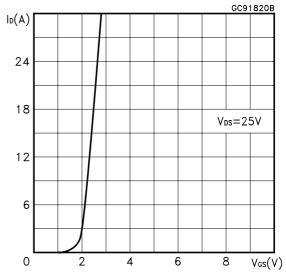
#### Transconductance



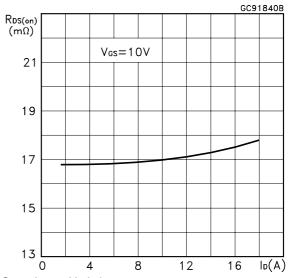
Gate Charge vs Gate-source Voltage



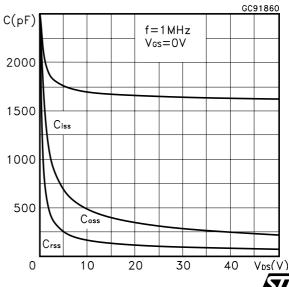
#### **Transfer Characteristics**



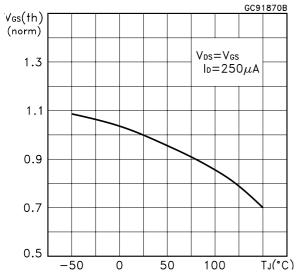
Static Drain-source On Resistance



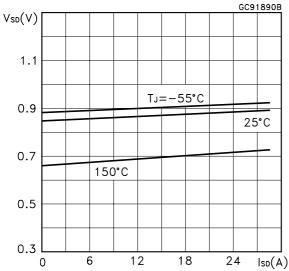
#### Capacitance Variations



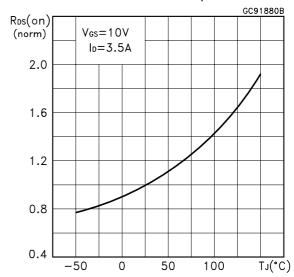
#### Normalized Gate Threshold Voltage vs Temperature



#### Source-drain Diode Forward Characteristics



#### Normalized on Resistance vs Temperature



#### Normalized Breakdown Voltage vs Temperature

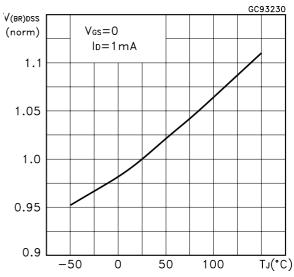


Fig. 1: Unclamped Inductive Load Test Circuit

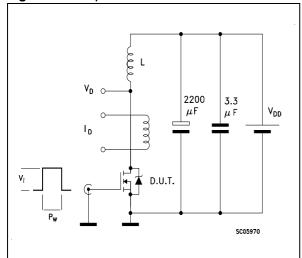
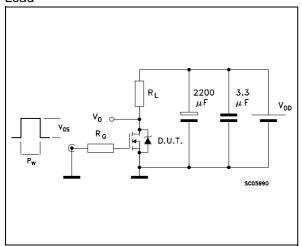


Fig. 3: Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times

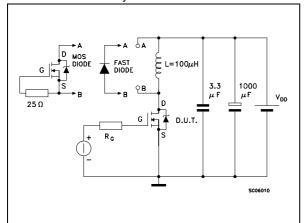


Fig. 2: Unclamped Inductive Waveform

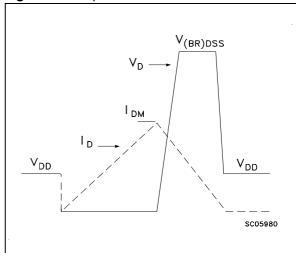
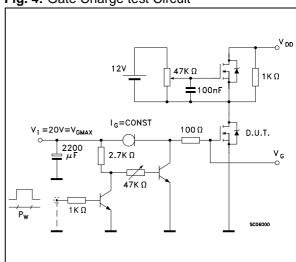
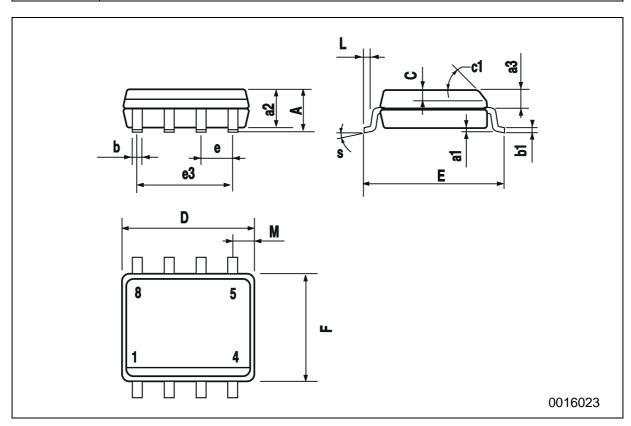


Fig. 4: Gate Charge test Circuit



## **SO-8 MECHANICAL DATA**

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		



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